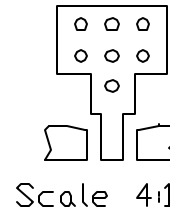
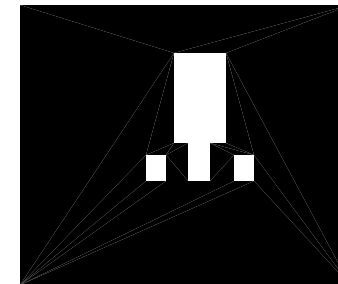


Alternate Backside Patterns
(May be supplied with any pattern shown.)

Caution: The Land Patterns and Solder Mask shown are generic for this package. Refer to product data sheet for any required variations specific to an application.



Scale 4:1
- Generic Land Pattern -
This land pattern is applicable to both backside patterns shown.



Scale 4:1
- Generic Solder Mask Opening -
This solder mask is applicable to both backside patterns shown.

UNLESS OTHERWISE SPECIFIED,
DIMENSIONS ARE IN mm (inches)
PER ANSI Y14.5M-1982.
TOLERANCES ARE:
DECIMAL ANGLE
.XX ±.12 (.005) ±1/2°
.XXX ±.05 (.002)

MATERIALS:
See Notes

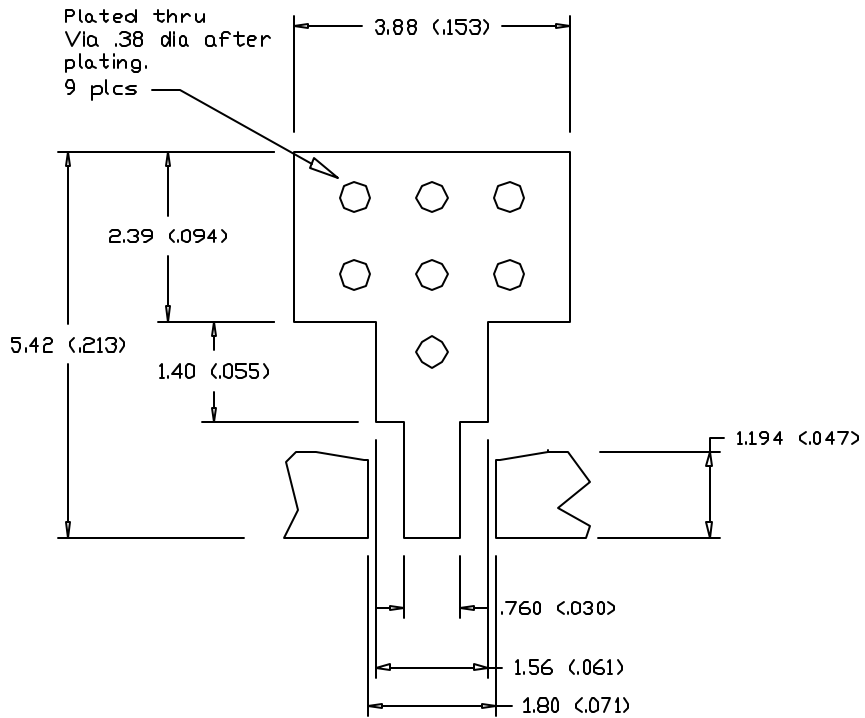
FINISH:
See Notes

Notes:
Base Metal - Copper Dln 194
Lead Finish
Basic PN - Sn/Pb Sn =>80%
Z option - 100% Matte Sn - .01 (.0004) thk min

- Do Not Scale Hardcopy -

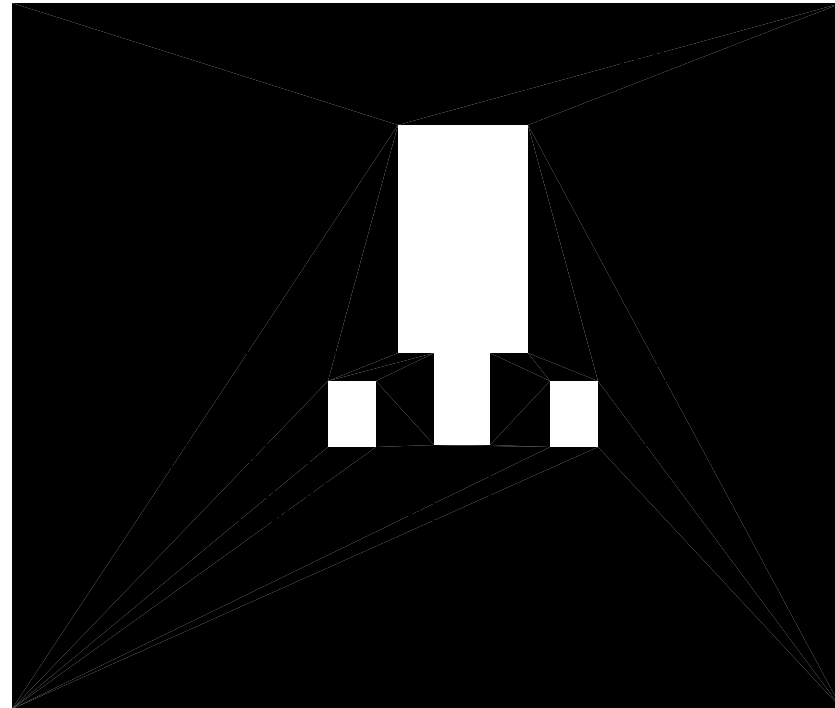


Package Type: SOT-89 4 Ld		
SMDI Package Type: XXX-XX89		
Dwg No. MPO-100136	Sht 1 of 2	REV J



Scale 10:1

- Generic Land Pattern -
This land pattern is applicable to
both backside patterns shown.



Scale 10:1

- Generic Solder Mask Opening -
This solder mask is applicable to
both backside patterns shown.

- Do Not Scale Hardcopy -

SIRENZA MICRODEVICES		
Package Type: SOT-89 4 Ld		
SMDI Package Type: XXX-XX89		
Dwg No. MPO-100136	Sht 2 of 2	REV J